Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-2. (Canceled)

3. (Currently Amended) The manufacturing process of conductive composition as in claim ~~2~~11, wherein said first slurry and said second slurry have substantially the same composition.

4. (Canceled)

5. (Currently Amended) The manufacturing process of conductive composition as in claim ~~2~~11, wherein an average particle size of said ceramics particles is less than that of said metal particles.

6. (Canceled)

7. (Currently Amended) The manufacturing process of conductive composition as in claim ~~2~~11, wherein an average particle size of said ceramics particles is a half of or less than an average particle size of said metal particles.

8. (Canceled)

9. (Currently Amended) The manufacturing process of conductive composition as in claim ~~2~~11, wherein an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles.

10. (Canceled)

11. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry~~The manufacturing process of conductive composition as in claim 2,~~,

wherein an average particle size of said metal particles is 0.5μm or less.

12. (Canceled)

13. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry~~The manufacturing process of conductive composition as in claim 5,~~,

wherein an average particle size of said ceramics particles is less than that of said metal particles, and

wherein an average particle size of said metal particles is 0.5μm or less.

14. (Canceled)

15. (Currently Amended) A manufacturing process of conductive composition including metal particles and ceramics particles, comprising the steps of:

wetting undried said metal particles having been water washed; and

colliding a first slurry including at least said wetted metal particles and said ceramics particles with a second slurry supplied along contrary different direction from the first slurry~~The manufacturing process of conductive composition as in claim 2,~~,

wherein said metal particles are Ni or Ni content compound.

16. (Canceled)

17. (Currently Amended) The manufacturing process of conductive composition as in claim ~~2~~11, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

18-21. (Canceled)

22. (New) The manufacturing process of conductive composition as in claim 13, wherein said first slurry and said second slurry have substantially the same composition.

23. (New) The manufacturing process of conductive composition as in claim 13, wherein an average particle size of said ceramics particles is a half of or less than an average particle size of said metal particles.

24. (New) The manufacturing process of conductive composition as in claim 13, wherein an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles.

25. (New) The manufacturing process of conductive composition as in claim 13, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.

26. (New) The manufacturing process of conductive composition as in claim 15, wherein said first slurry and said second slurry have substantially the same composition.

27. (New) The manufacturing process of conductive composition as in claim 15, wherein an average particle size of said ceramics particles is less than that of said metal particles.

28. (New) The manufacturing process of conductive composition as in claim 15, wherein an average particle size of said ceramics particles is a half of or less than an average particle size of said metal particles.

29. (New) The manufacturing process of conductive composition as in claim 15, wherein an average particle size of said ceramics particles is a quarter of or less than an average particle size of said metal particles.

30. (New) The manufacturing process of conductive composition as in claim 15, wherein said conductive composition is a conductive paste to form an electrode on ceramic dielectric substrate.